

Part Number: **MMBZ52xxB-(p)-F (Date Code 0833+)**
Weight (mg): 8.4874

p = package designator
See Data Sheet

x= 21, 22, 23, 25, 26, 27, 28, 29, 30, 31, 32, 33, 34, 35, 36,
37, 38, 39, 40, 41, 42, 43, 44, 45, 46, 48, 50, 51, 52, 54, 55,
56, 57, 58, 59

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon *	7440-21-3	100.00%	0.76	0.0647	1000000	7623
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	28.79	2.4432	576500	165952
		Ni	7440-02-0	41.00%			410000	118023
		Mn	7439-96-5	0.60%			6000	1727
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	288
		Co	7440-48-4	0.50%			5000	1439
		Si	7440-21-3	0.15%			1500	432
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.22	0.1034	1000000	12183
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.10	0.0082	1000000	966
Encapsulation	KTMC1050G	Silica	60676-86-0	77.00%	66.13	5.6124	770000	509172
		Basic Duromer: Epoxy resin (Compound of a polymeric network)	----	11.00%			110000	72739
		Basic Duromer:Phenolic resin (Compound of polymeric network)	----	6.60%			66000	43643
		Misc. system	system	5.00%			50000	33063
		Carbon black	1333-86-4	0.40%			4000	2645
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	3.01	0.2555	1000000	30103
				Total	100.00	8.4874		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Hexavalent chromium compounds	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Lead and lead compounds	Radioactive Substances
Mercury and mercury compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Organic tin compounds	Tributyl Tin Oxide (TBTO)